



**THE DATASHEET OF
GP1A054RDKLF**



GP1A054RDKLF

Case Type
With Encoder Function
Digital 2 Output (A Phase / B Phase)
Transmissive Photointerrupter



■Description

GP1A054RDKLF is a transmissive photointerrupter with digital 2 output (phase A/B) encoder function. Using this with a linear scale (or rotation disk) that forms a slit pattern, this product detects the movement (rotation) direction and the amount of movement (number of revolutions, rotation angle).

This product has mounting holes for screwing to a substrate.

■Features

1. Transmissive Photointerrupter
2. Case type, with encoder function
3. Output signal : Digital 2 output (A Phase / B Phase)
4. Resolution : Linear scale slit pitch 0.0847 [mm]
(300LPI)

■Agency approvals/Compliance

1. Compliant with RoHS directive (2002/95/EC)

■Applications

1. Detects direction of movement, the amount of movement, rotation angle of equipment and device that move horizontally or rotate.
Example : printer, copier, robot, motor control, etc.

Notice The content of data sheet is subject to change without prior notice.

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

Sheet No.: OP13027EN

■ Outline

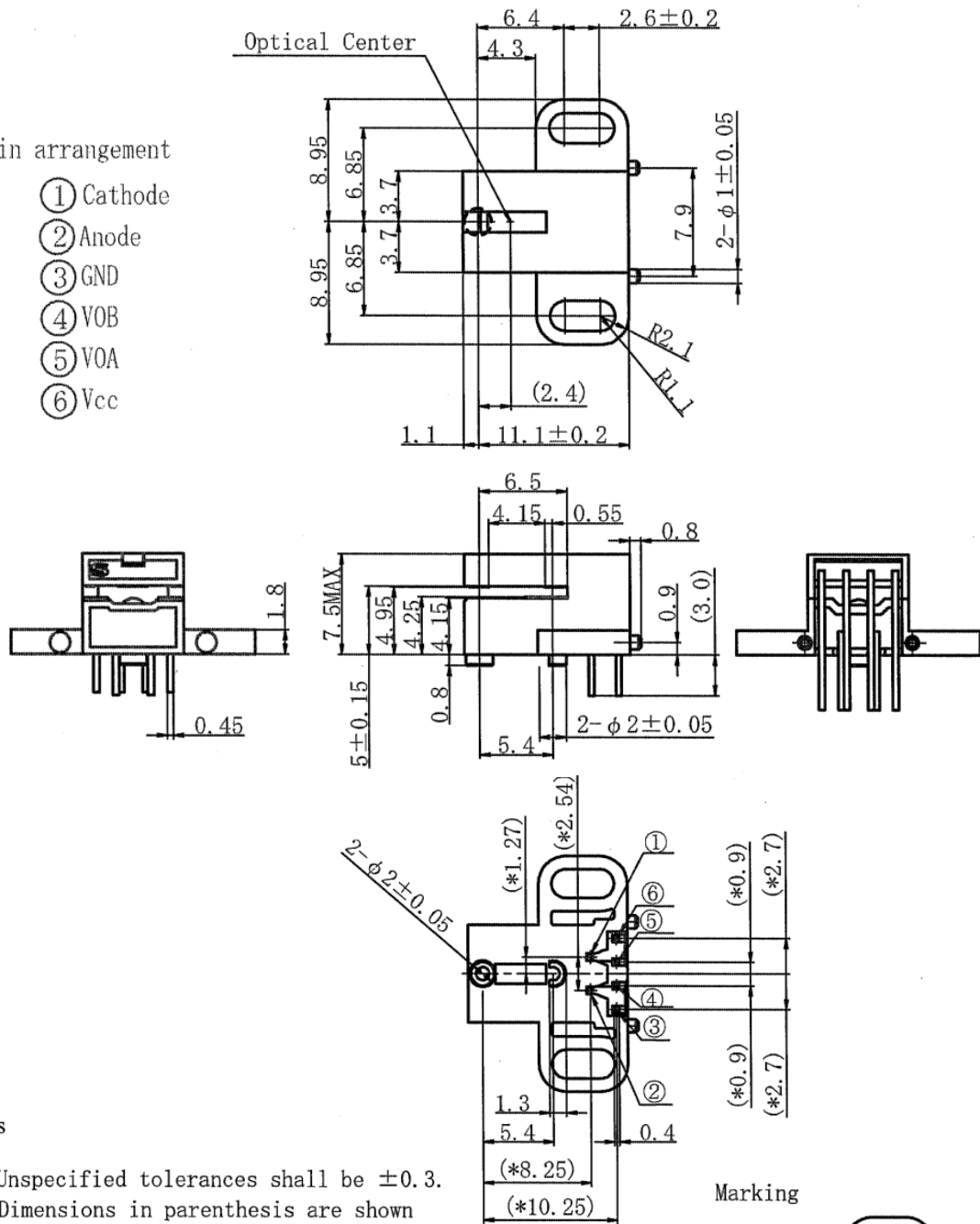
Drawing No.CY14716i02A

Scale : 2/1

Unit : mm

Pin arrangement

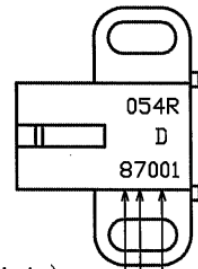
- ① Cathode
- ② Anode
- ③ GND
- ④ VOB
- ⑤ VOA
- ⑥ Vcc



Notes

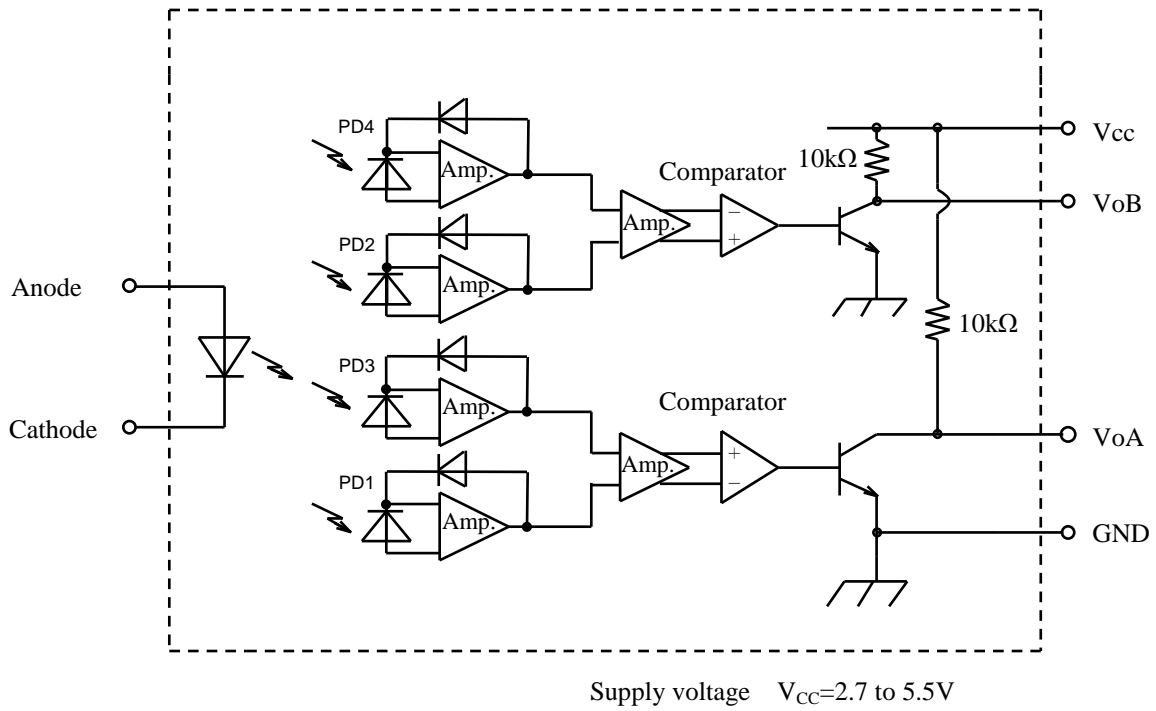
- 1) Unspecified tolerances shall be ±0.3.
- 2) Dimensions in parenthesis are shown for reference.
- 3) The dimensions indicated by * refer to the those measured from the lead base.
- 4) Datecode is 5 digit.
 - (Production year)
The last number of the year.
 - (Production Month)
From 1 to 9, it mean January to September.
X is October, Y is November and Z is December.
 - (Production Lot)
001 means Production Lot No. "001"

Marking



- Production year (1 digit)
- Production Month (1 digit)
- Production Lot (3 digit)

■Block diagram



■Absolute maximum ratings

$T_a=25^{\circ}C$

| Parameter | | Symbol | Rating | Unit |
|--------------------------|--------------------------|-----------|------------|-------------|
| Input | Forward current *1 | I_F | 30 | mA |
| | Reverse voltage | V_R | 4 | V |
| Output | Supply voltage | V_{CC} | 6 | V |
| | Low level output current | I_{OL} | 8 | mA |
| | Power dissipation *1 | P_o | 150 | mW |
| Operating temperature | | T_{opr} | -10 to +70 | $^{\circ}C$ |
| Storage temperature | | T_{stg} | -40 to +80 | $^{\circ}C$ |
| Soldering temperature *2 | | T_{sol} | 260 | $^{\circ}C$ |

*1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1, 2.

*2 Soldering time : 5s or less

■ **Electro-optical characteristics**

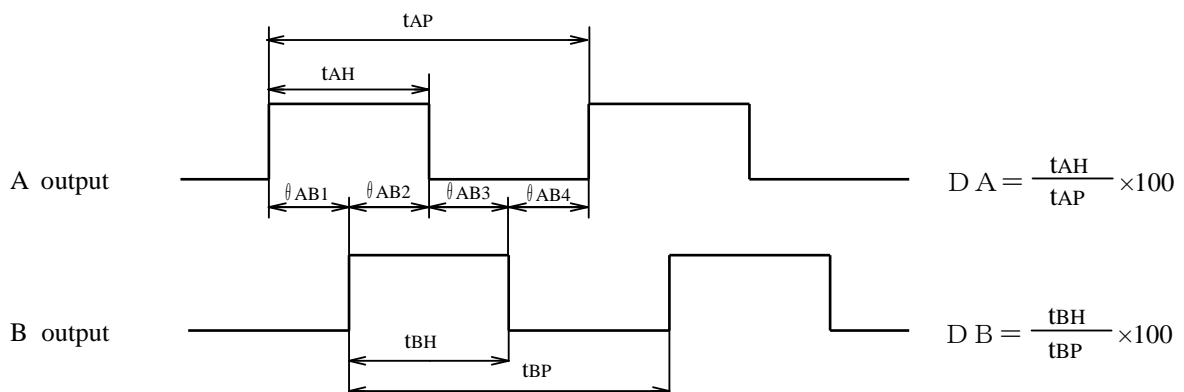
Ta=25°C

| Parameter | | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|--------------------------------|--------------------------------|---|---|------|------|------|------|
| Input | Forward voltage | V _F | I _F =20mA | - | 2.1 | 2.6 | V |
| | Reverse current | I _R | V _R =1V | - | - | 100 | μA |
| Output | Operating supply voltage range | V _{CC} | - | 2.7 | 3.3 | 5.5 | V |
| | Low level output voltage | V _{OL} | V _{CC} =3.3V, I _F =20mA I _{OL} =8mA | - | - | 0.4 | V |
| | High level output voltage | V _{OH} | V _{CC} =3.3V, I _F =20mA | 2.4 | 3.2 | - | V |
| | Supply current | I _{CC} | V _{CC} =3.3V, I _F =20mA Phases A and B both at low level | - | 2.2 | 5.5 | mA |
| Transfer characteristics *1 | Duty | D _A | V _{CC} =3.3V I _F =20mA f=20kHz | 35 | 50 | 65 | % |
| | | D _B | | | | | |
| | Phase difference | θ _{AB1 to 4} | | 45 | 90 | 135 | ° |
| | Response | tr | | - | 1.0 | 2.0 | μs |
| | | tf | | - | 1.0 | 2.0 | |
| Response frequency | fmax | V _{CC} =3.3V, I _F =20mA | - | - | 40 | kHz | |

- *1 The test condition is according to Fig.3 (CY14717i06)
And transfer characteristics value does not include any error of code-wheel (Liner scale).
The error of slit-pattern shall not be included.
- *2 The code-wheel (Liner scale) surface (patterned surface) shall be arranged face to face with detector holder surface.
The code-wheel (Liner scale) shall not contact with the holder surface.

Note: It is recommended that the GP1A054RDKLF be used under the condition of typical I_F=20mA for which it is designed.

■ **Output waveform**



Refer to note 1 in Fig.3 (CY14717i06) for the rotation direction of code-wheel (Liner scale).

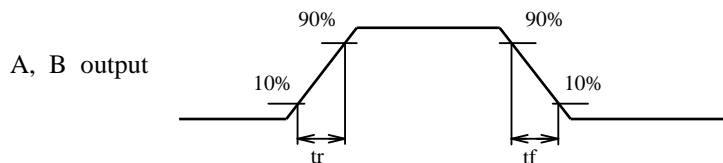


Fig.1 Forward current vs. ambient temperature

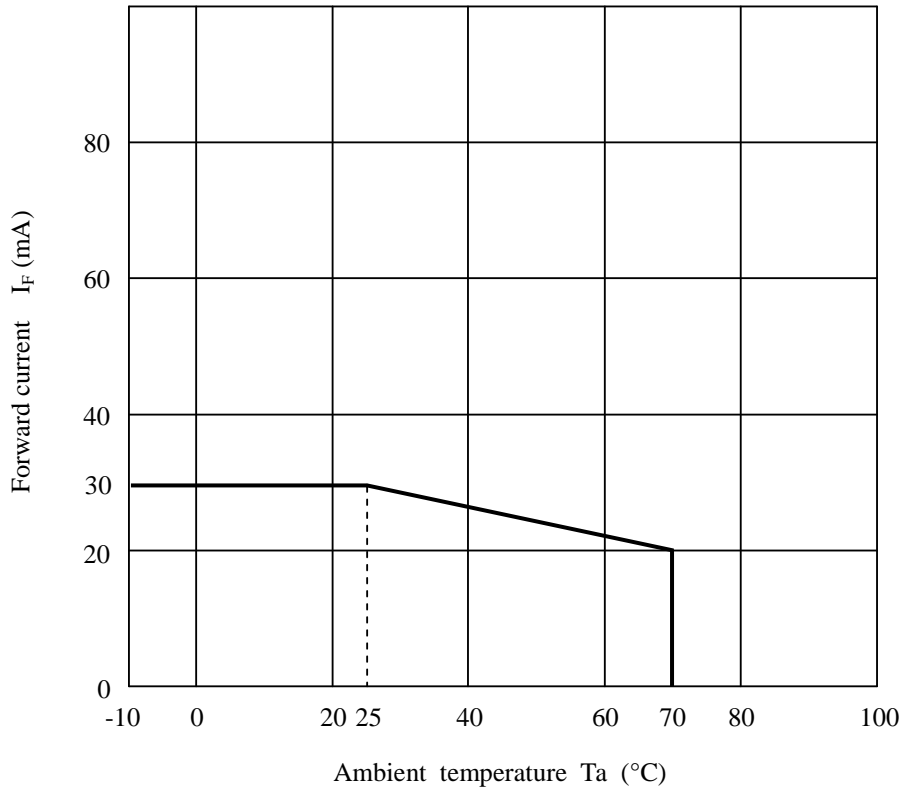


Fig.2 Output power dissipation vs. ambient temperature

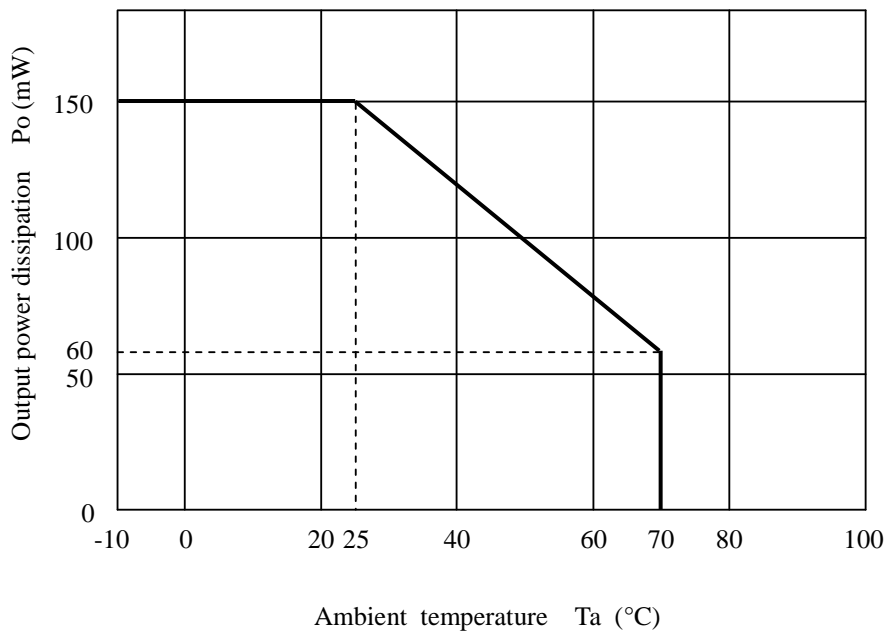
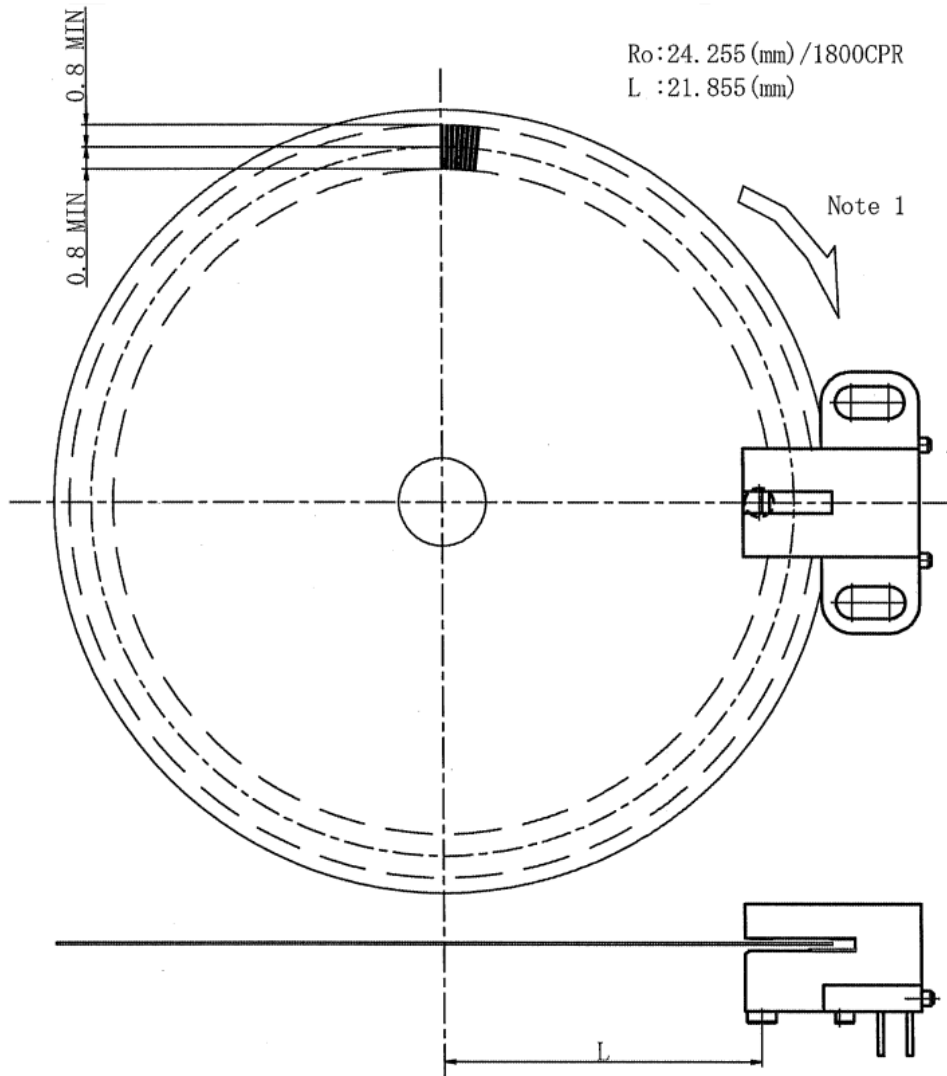
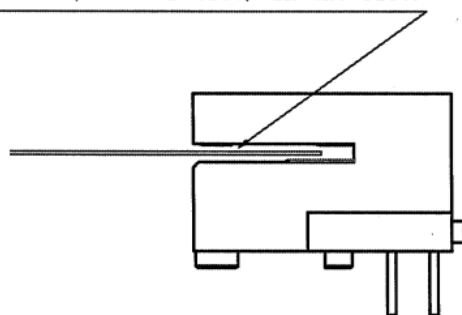


Fig.3 GP1A054RDKLF Test Condition (Drawing No.CY14717i06) Scale : Free Unit : 1/1mm



Please make sure the code-wheel(Liner scale) surface.
(slit patterned surface) is upper side
(Detector side) in the side.



Notes

- 1) The rotation direction of code-wheel(Liner scale) against output waveform (Refer to 3.4).
- 2) The code-wheel(Liner scale) shall not contact with the holder surface.

■ **Supplements**

● **Parts**

Refer to the attached sheet, Page 9.

● **Packing**

Refer to the attached drawing No. CY14718i09A, Page 10.

● **ODS materials**

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methyl chloroform)

● **Specified brominated flame retardants**

Specified brominated flame retardants (PBB and PBDE) are not used in this device at all.

● **Compliance with each regulation**

1) The RoHS directive(2002/95/EC)

This product complies with the RoHS directive(2002/95/EC)

Object substances: mercury,lead, cadmium,hexavalent chromium,polybrominated biphenyls (PBB)

and polybrominated diphenyl ethers (PBDE)

2) Content of six substances specified in Management Method for Control of Pollution Caused by Electronic

Information Products Regulation (Chinese : 电子信息产品污染控制管理办法).

| Category | Toxic and hazardous substances | | | | | |
|------------------|--------------------------------|--------------|--------------|---|--------------------------------|---------------------------------------|
| | Lead (Pb) | Mercury (Hg) | Cadmium (Cd) | Hexavalent chromium (Cr ⁶⁺) | Polybrominated biphenyls (PBB) | Polybrominated diphenyl ethers (PBDE) |
| Photointerrupter | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ |

✓ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

● **Product mass : Approximately 0.65g**

● **Country of origin : Japan, China, Indonesia**

■Notes

- The recommendation conditions of forward current:
This product is designed in consideration of using this product under the condition of typical $I_F=20\text{mA}$ as a standard.
- In order to stabilize power supply line, it is recommended to have a by-pass capacitor of $0.1\mu\text{F}$ or more between V_{CC} and GND near the device.
- Lens is made from resin, as to cleaning, this photointerrupter should not be cleaned by cleaning materials absolutely. (Dust and stain shall be cleaned by air blow.)
- Soldering
To solder onto lead pins, please solder at 260°C for 5s or less with longer distance than 1.6mm from the bottom surface of the package.
Please take care not to let any external force exert on lead pins when soldering or just after soldering.
Please don't do soldering by reflow.
- OPIC chip due to micro design is easily affected by the Electro static discharge.
At operating, in order to prevent the destruction and the defect of characteristics by Electro static discharge, please take a general countermeasure of the Electro static discharge.
- Prevention of malfunction
For this product, the transparent material is used as the case material .
Before using this product, please confirm the following items with the actual equipment.
1) The product does not malfunction by the ambient light illuminating the photo-detector surface.
2) Other equipment is not affected by the light leaking from the light-emitting device.
- Assembly of the device
When tightening this product with the screw, please use the M2.6 machine screw. The recommended tightening torque with M2.6 machine screw is 0.25 to 0.35 N · m.
However, this recommended tightening torque is the reference value because the tightening torque varies according to the screw and the bolted joint.
Before tightening the screw, please certainly confirm the tightening strength of this product and the object on which this product is mounted
Also, when tightening the screw with the tools such as the screw-driver, if the pushing force by the screw-driver is too strong, the damage of the product performances such as the break of the holder's mounting hole may be caused by the application of the external force. Therefore, please be careful not to apply such a force to this product.
- Storage and usage environment
Polycarbonate is used as the case material of this product.
If polycarbonate contacts with the hot liquid and the alkaline solution (alkaline atmosphere), polycarbonate is hydrolyzed. Therefore, please do not store and use this product in such an environment.

■Parts

This product uses the below parts.

- Light detector (Quantity : 1)
(Using a silicon photodiode as light detecting portion, and a bipolar IC as signal processing circuit.)

| Type | Maximum sensitivity wavelength (nm) | Sensitivity wavelength (nm) | Response time (μs) |
|------------|-------------------------------------|-----------------------------|--------------------|
| Photodiode | 780 | 400 to 1200 | 25 |

- Light emitter (Quantity : 1)

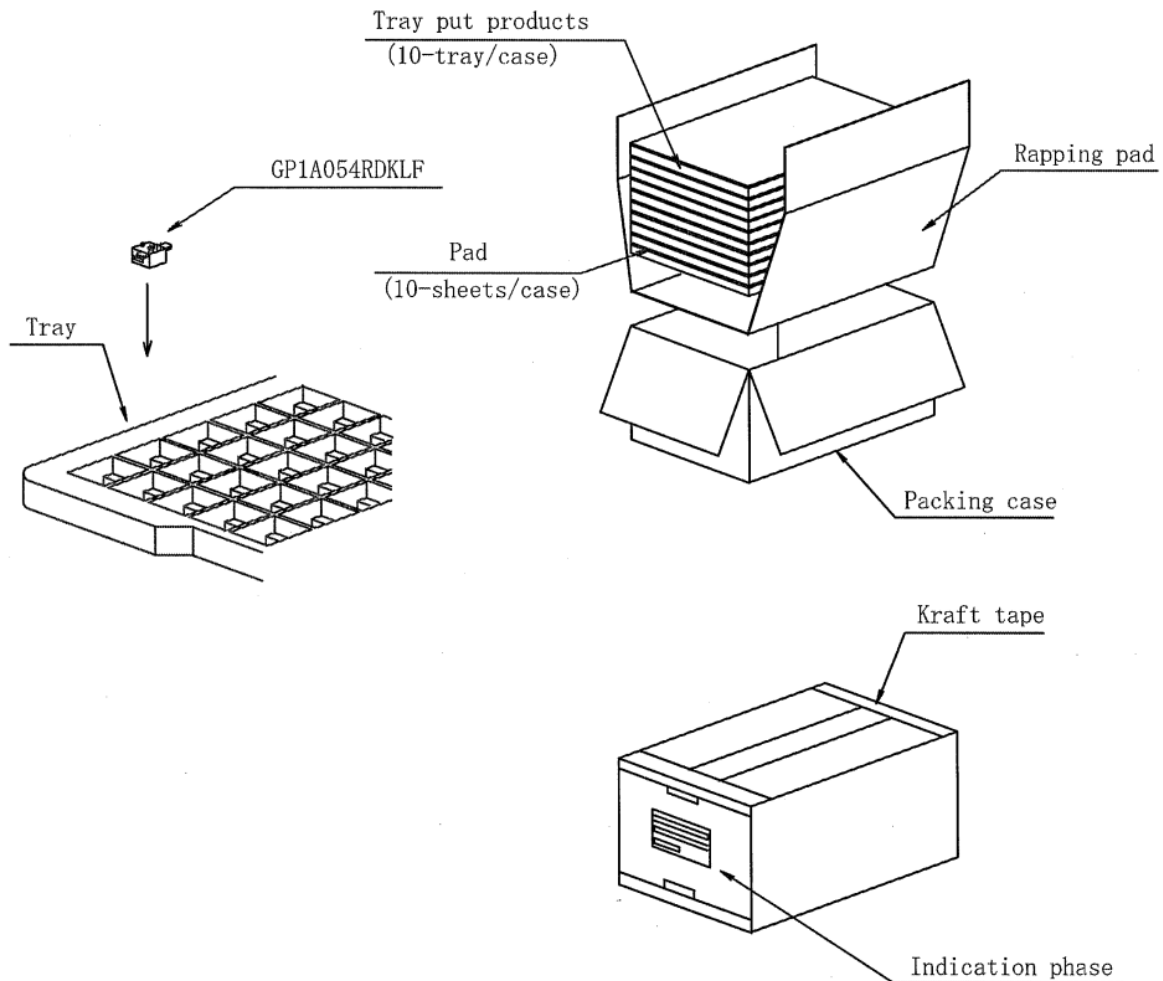
| Type | Material | Maximum light emitting wavelength (nm) |
|-------------------------------------|---------------|--|
| Light emitting diode (Non-coherent) | AlGaInP /GaAs | 652 |

- Material

| | |
|---------------------------------|-----------------------|
| Holder integrated with Lens | Lead flame finish |
| Transparent polycarbonate resin | Solder dip (Sn-Ag-Cu) |

- Others
This product shall not be radiation flux proof.
Laser generator is not used.

■Packing (Drawing No.:CY14718i09A)



1) Package materials

- Outer package : Packing case (Paper corrugated cardboard)
- Inner package : Pad (Polyethylene)
Rapping pad (Paper corrugated cardboard)
Tray (Polystyrene)

2) Packaging number

- Max. 100 pieces per tray
- Max. 1000 pieces per case

3) Package specifications

- Put them (10 tray) in the packing box.
- Put pads on the top of each tray.
- Seal the packing box with kraft tape.

4) Indication items

- The contents of the carton indication conforms to EIAJ C-3 and the following items are indicated.
Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin.

5) Regular packing mass

- (Excluding fractions, however above packing material, packing count, packing style)
- Approximately 2.1kg

■ Important Notices

· The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

· Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.

· Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

· If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.

· This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.

· Contact and consult with a SHARP representative if there are any questions about the contents of this publication.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View GP1A054RDKLF on WIN SOURCE](#)
- ⊖ [Sharp Microelectronics Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management